

Subject card

Subject name and code	Design Methodology and Manufacturing, PG_00048073							
Field of study	Electronics and Telecommunications							
Date of commencement of studies	October 2023		Academic year of realisation of subject			2025/2026		
Education level	first-cycle studies		Subject group		Optional subject group Subject group related to scientific research in the field of study			
Mode of study	Full-time studies		Mode of delivery			at the university		
Year of study	3		Language of instruction			Polish		
Semester of study	5		ECTS credits			1.0		
Learning profile	general academic profile		Assessment form			assessment		
Conducting unit	Department of Metrol	Department of Metrology and Optoelectronics -> Faculty of Electronics, Telecor				elecom	munications ar	nd Informatics
Name and surname	Subject supervisor		dr inż. Arkadiusz Szewczyk					
of lecturer (lecturers)	Teachers		dr inż. Arkadiusz Szewczyk					
Lesson types and methods	Lesson type	Lecture	Tutorial	Laboratory	Projec	Project Seminar		SUM
of instruction	Number of study hours	15.0	0.0	0.0	0.0		0.0	15
	E-learning hours included: 0.0							
Learning activity and number of study hours	Learning activity	Participation in classes include plan		Participation in consultation hours		Self-study		SUM
	Number of study 15 hours			1.0		9.0		25
Subject objectives	Give the knowledge of technology of design and manufacturing of electronic equipment.							
Learning outcomes	Course outcome Subject outcome Method of verification							
	required specifications, and make a simple device, facility, system or carry out a process, specific to the field of study, using suitable methods, techniques, tools and materials, following engineering standards and norms, applying technologies specific to the field of study and experience gained in the professional engineering environment		is able to design, in accordance with the given specification, and build a simple electronic device			[SU1] Assessment of task fulfilment		
						[SW1] Assessment of factual knowledge		
Subject contents Prerequisites	1. Basic problems of designing and engineering of electronic devices and systems.2. Designing of electronic devices allowing requirements of manufacturing3. Factors determining designing and construction processes. Optimal solutions. 4. Enclosure and module systems. 5. Internal connections between modules: fixed and separable. 6. Elements with contacts; matching of modules. 7. Cabling. Parameters of cables, materials for conducting wires, isolators and shields. 8. Connection techniques: soldering, wire-wrapping, crimping. 9. Manual and automatic soldering. 10. Influence of the electronic devices mounting technology on environment; lead-free soldering, flux materials. 11. Electronic components for through-hole and surface mounting technology. 12. Surface mounting technology. Wave soldering, reflow soldering. 13. Production units for automatic mounting of electronic components. Automatic units for components positioning, for depositing of glue and solder. 14. Designing of pads. Influence of the mounting technology on printed board design. 15. Construction and techniques of printed circuit boards manufacturing. 16. Electronic Design Automation (EDA) software. 17. Preparation of fabrication documentation. 18. Grounding and shielding techniques. Designing of shields. 19. Cooling systems in electronic devices. Designing of the cooling systems and radiators for the typical power components.							
and co-requisites	1							

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Assessment methods	Subject passing criteria	Passing threshold	Percentage of the final grade			
and criteria	Writting exam	50.0%	100.0%			
Recommended reading	Basic literature	Ryszard Kisiel: "Podstawy technologii montażu dla elektroników", BTC 2012				
	Supplementary literature	Krystyna Bukart, Halina Hackiewicz: "Lutowanie bezołowiowe", BTC 2007				
	eResources addresses	Adresy na platformie eNauczanie:				
Example issues/ example questions/ tasks being completed	CAD software, soldering, PCB assembly, devices outlines, connections, grounding, shielding.					
Work placement	Not applicable					

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